DuPont™ Posistrip®
EKC800™ Series
Photoresist Removers
For Positive Photoresist Removal

**Product Description**
DuPont™ Posistrip® photoresist removers are organic blends specifically formulated to remove positive photoresist from substrate surfaces used in the microelectronics industry.

Formulated to meet a wide range of process requirements, Posistrip® products vary from mildly aggressive non-alkaline chemistries for removal of photoresist from sensitive metal layers or substrates like GaAs, to very aggressive alkaline chemistries for removal of extremely hardened photoresist. These water-rinsable formulations allow the user to complete the photoresist removal process with less chemistry and lower cost of ownership (CoO). These products are low in metal ions, non-corrosive to sensitive metals and contain no phenol or chlorinated solvents. Posistrip® products are compatible with automatic equipment allowing for easy conversion from manual wet station environments.

**DuPont™ Posistrip® EKC800™ Series photoresist removers include:**

**Posistrip® EKC800™**
Designed to remove positive photoresist that has experienced standard processing with normal thermal history.

**Posistrip® EKC830™**
Designed to effectively remove positive photoresist resulting from harsh prior processing that is difficult to remove.

**Posistrip® EKC865™**
Specifically formulated to prevent attack of sensitive metals. Removes positive photoresist with normal thermal history.
For more information on DuPont™ Posistrip® EKC800™ or other DuPont products, please visit our website.

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